

REMARKS

The Office Action dated March 22, 2004, has been received and reviewed.

Claims 1-20 were previously pending and under consideration in the above-referenced application, each standing rejected.

New claim 21 has been added.

Reconsideration of the above-referenced application is respectfully requested.

Information Disclosure Statement

Please note that an Information Disclosure Statement was filed in the above-referenced application on August 22, 2003, but that the undersigned attorney has not yet received any indication that the references cited in the Information Disclosure Statement have been considered in the above-referenced application. It is respectfully requested that the references cited in the Information Disclosure Statement of August 22, 2003, be considered and made of record in the above-referenced application and that an initialed copy of the Form PTO/SB/08A that accompanied that Information Disclosure Statement be returned to the undersigned attorney as evidence of such consideration.

Rejections Under 35 U.S.C. § 112, Second Paragraph

Claims 6 and 7 stand rejected under 35 U.S.C. § 112, second paragraph, for reciting subject matter that is purportedly indefinite.

Claims 6 and 7 have been amended to remove the term “the” in front of “another semiconductor device.” These revisions should not be construed as narrowing the scope of either claim 6 or claim 7.

It is respectfully submitted that claims 6 and 7 comply with the definiteness requirement of the second paragraph of 35 U.S.C. § 112.

Rejections Under 35 U.S.C. § 102

Claims 1-18 have been rejected under 35 U.S.C. § 102.

A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single reference which qualifies as prior art under 35 U.S.C. § 102. *Verdegaal Brothers v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

Haba

Claims 1-7 stand rejected under 35 U.S.C. § 102(e) for reciting subject matter which is purportedly anticipated by the subject matter described in U.S. Patent 6,376,904 to Haba et al. (hereinafter “Haba”).

Amended independent claim 1 recites a method for designing a rerouting element. A base substrate of the rerouting element is configured with at least one contact location adjacent to a first peripheral edge and at least one rerouted bond pad location adjacent to a second peripheral edge, which is opposite from the first peripheral edge. The at least one contact location is configured to mirror a position of at least one substantially centrally located bond pad of a semiconductor device.

In contrast, the description of Haba is limited to rerouting elements that cover the entire surfaces of semiconductor devices. Thus, a method for designing such a rerouting element for use with a semiconductor device that includes substantially centrally located bond pads would include configuring at least one contact location substantially centrally on a base substrate of the rerouting element, rather than adjacent to a peripheral edge thereof.

Even centrally located bond pads that are positioned adjacent to an edge of the base substrate of the rerouting element disclosed in Haba are rerouted to rerouted bond pad locations adjacent to the next (*i.e.*, an adjacent) peripheral edge of the base substrate.

Therefore, Haba does not expressly or inherently describe configuring at least one contact location adjacent to a peripheral edge of a base substrate and at least one rerouted bond pad location adjacent to an opposite peripheral edge of the base substrate. Thus, Haba does not anticipate each and every element of amended independent claim 1, as would be required to maintain the 35 U.S.C. § 102(e) rejection of that claim.

Each of claims 2-7 is allowable, among other reasons, for depending directly or indirectly from claim 1, which is allowable.

Golshan

Claims 1-3 and 5 are rejected under 35 U.S.C. § 102(e) for being drawn to subject matter that is allegedly anticipated by the disclosure of U.S. Patent 5,384,488 to Golshan et al. (hereinafter “Golshan”).

Like Haba, Golshan also lacks any express or inherent description of a method for designing a rerouting element that includes configuring at least one contact location adjacent to a peripheral edge of a base substrate and at least one rerouted bond pad location adjacent to an opposite peripheral edge of the base substrate.

The description of Golshan is instead limited to designing rerouting elements with substantially centrally located contact locations and to methods that include configuring contact locations adjacent to one peripheral edge of a base substrate of a rerouting element and configuring bond pad locations adjacent to the next, adjacent peripheral edge of the base substrate.

For these reasons, Golshan does not anticipate each and every element of amended independent claim 1. Accordingly, it is respectfully submitted that, under 35 U.S.C. § 102(e), amended independent claim 1 recites subject matter which is allowable over that described in Golshan.

Each of claims 2, 3, and 5 is allowable, among other reasons, for depending directly or indirectly from claim 1, which is allowable.

Haba

Claims 8-18 have been rejected under 35 U.S.C. § 102(e) for being drawn to subject matter that is assertedly anticipated by the subject matter described in Haba.

Independent claim 8 is drawn to an assembly method that includes providing a first semiconductor device and positioning a rerouting element over the first semiconductor device. A second semiconductor device is positioned over the first rerouting element, with a first rerouted

bond pad location of the first rerouting element being located adjacent to and exposed laterally beyond a peripheral edge of the second semiconductor device. A second rerouting element is positioned on the second semiconductor device, with a second rerouted bond pad location being positioned adjacent to another, opposite edge of the second semiconductor device.

Haba includes no express or inherent description of a method that includes assembling first and second semiconductor devices and corresponding rerouting elements in this manner. Instead, the disclosure of Haba is limited to assembly methods in which *rerouted* bond pad locations are adjacent to a single surface of the assembly (Haba does not expressly or inherently describe that the bond pads that are located adjacent to the right side of the assembly shown in Fig. 13 of *rerouted* bond pads).

Thus, Haba does not anticipate each and every element of amended independent claim 8, as would be required to maintain the 35 U.S.C. § 102(e) rejection of amended independent claim 8.

Each of claims 9-18 is allowable, among other reasons, for depending directly or indirectly from claim 8, which is allowable.

Withdrawal of the 35 U.S.C. § 102(e) rejections of claims 1-18 is respectfully solicited.

Rejections Under 35 U.S.C. § 103(a)

Claims 19 and 20 stand rejected under 35 U.S.C. § 103(a) for reciting subject matter which is purportedly unpatentable over the teachings of Haba.

Claims 19 and 20 are each allowable, among other reasons, for depending either directly or indirectly from claim 8, which is allowable.

New Claim

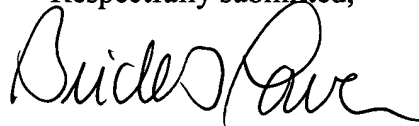
New claim 21 has been added. New claim 21 depends from amended independent claim 8, and recites a assembly method that includes positioning a third semiconductor device and a third rerouting element over the second rerouting element of amended independent claim 8. Third rerouted bond pad locations of the third rerouting element are located adjacent to an

opposite peripheral edge of the third semiconductor device from the peripheral edge adjacent to which the second rerouted bond pad locations of the second rerouting element are located and, thus, adjacent to the same side of the assembly as the first rerouted bond pad locations. It is respectfully submitted that new claim 21 does not introduce new matter into the above-referenced application. It is also submitted that the subject matter recited in new claim 21 is not expressly or inherently described in, or taught or suggested by, Haba or Golshan.

CONCLUSION

It is respectfully submitted that each of claims 1-21 is allowable. An early notice of the allowability of each of these claims is respectfully solicited, as is an indication that the above-referenced application has been passed for issuance. If any issues preventing allowance of the above-referenced application remain which might be resolved by way of a telephone conference, the Office is kindly invited to contact the undersigned attorney.

Respectfully submitted,



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